Meltex

Invitation to NEPCON JAPAN 2019

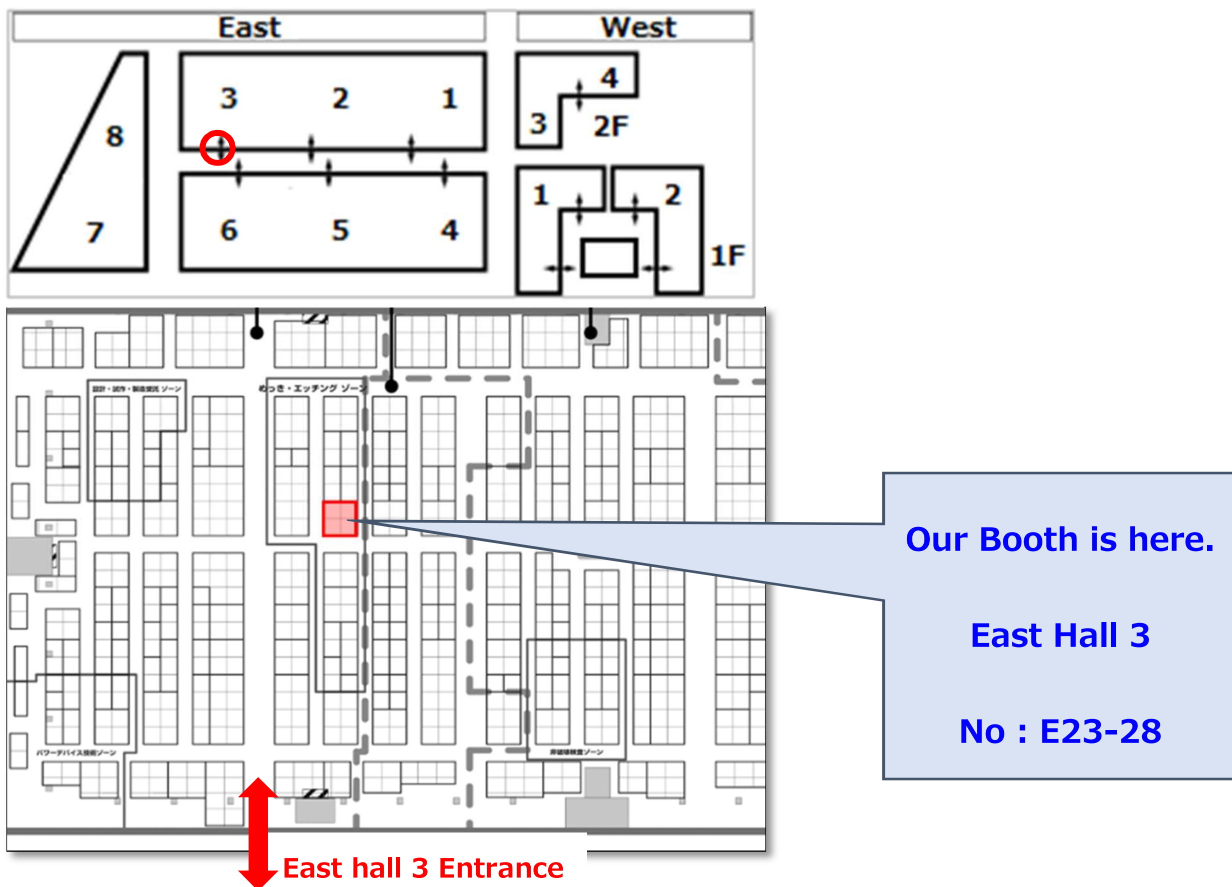
To Our Valued Customers:

We are pleased to inform you that we will be exhibiting at upcoming NEPCON JAPAN 2019 at Tokyo Big Sight, Japan. It is our honor to invite you to our booth and share the specific details about our products and technologies.

【Our booth】

Our booth will be located at E23-28 in East Hall 3.

Date : January 16(Wed) – January 18(Fri)
Time : 10:00am – 6:00pm on Jan.16&17
10:00am – 5:00pm on Jan.18
Venue : Tokyo Big Sight
Access: http://www.bigsight.jp/english/hotel/transportation/



Please find enclosed invitation tickets for the show. If you would like more tickets for your colleagues, do not hesitate to contact us anytime.

We will look forward to seeing you at our booth.

Yours faithfully,

【At our booth, we will be exhibiting as below】

□Melplate UBM Process	UBM (Under Barrier Metal) formation with electroless nickel and immersion gold plating on aluminum electrodes of semiconductor wafer
□Seed Layer Etchant for Semiconductor Wafer Application	Various etchants for sputtered copper or titanium seed/barrier layer
□Dry Film Resist Stripper for Semiconductor Wafer Application	TMAH free dry film resist stripper No attack on copper, aluminum, titanium and solder
□Products for Fan-Out packaging process － LtF Process －	LtF S-45 : Dry film resist stripper Amine based dry film resist stripper; minimum dissolution of fine copper pattern LtF E-52 : Copper seed layer etchant Halogen free, ammonia alkaline etchant LtF E-53 : Titanium seed layer etchant Hydrogen peroxide type etchant; applicable to immersion, spin and spray etching
□Copper/copper alloy roughening treatment for lead frames	Chemical roughening process for surface of various lead frame materials, resulting in adhesion enhancement between lead frame and molding compound

【PWB EXPO Technical Session】

Trends of Surface Treatment Chemicals in M-SAP for Fabrication of Fine Pattern.

【Detail】

In this presentation, an overview of the chemicals which are used for DFR stripping and Cu seed layer etching in M-SAP, as well as the current approaches for Fabrication of Fine Pattern and pattern shape after etching, are reported.

【Profile】

Shigeru Watariguchi
Team Leader
Research & Development, Technology Development Dept.

【Detail of Session】

Date : January 16(Wed)
Time : 9:30am － 12:00pm
Session NO : PWB-2
Fee : ￥27,000

※PWB - 2 All sessions can be audited.

Venue : Tokyo Big Sight conference building